PRESS RELEASE

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TopLine to Exhibit Solutions at IC & Sensor Packaging Technology Expo, Tokyo

Irvine California, USA – TopLine will exhibit at the IC & Sensor Packaging Technology Expo, one of the seven shows concurrently hosted under one roof at the Tokyo Big Sight during the 47th Nepcon, January 17-19, 2018. At the expo, TopLine will introduce CCGA Column Grid Array technology as well as Vibration Damping for extending the life of Printed Circuit Boards.

TopLine CCGA Column

TopLine CCGA Column Grid Array IC packages are made with high temperature solder columns for Surface Mount (SMT) soldering on Printed Circuit Boards (PCBs). CCGA packages provide more compliancy than BGA solder balls (Ball Grid Arrays) to absorb stress caused by CTE mismatch and increase solder joint reliability under harsh operating conditions.

TopLine's Particle Impact Dampers (PID) reduce random vibration in PCB board assemblies in harsh environments. "Reducing harmful vibrations extends hardware life and reliability," states Martin Hart, President.

TopLine will be reaching out to customers at the show to introduce them to these enabling technologies. TopLine has been continuously active in promoting solutions-oriented products in the global market for 28 years. The show is expected to bring 35,000 visitors from Japan, China and Korea.

About TopLine

TopLine manufactures a wide range of Daisy Chain test components and engineering evaluation kits for process development, experimentation, machine evaluation, solder training, and SMT assembly practice. TopLine products provide hands-on learning for engineers. Contact TopLine Corporation, Tel (+1) 800-776-9888; Email: info@TopLine.tv; or visit our web site, www.TopLine.tv.

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